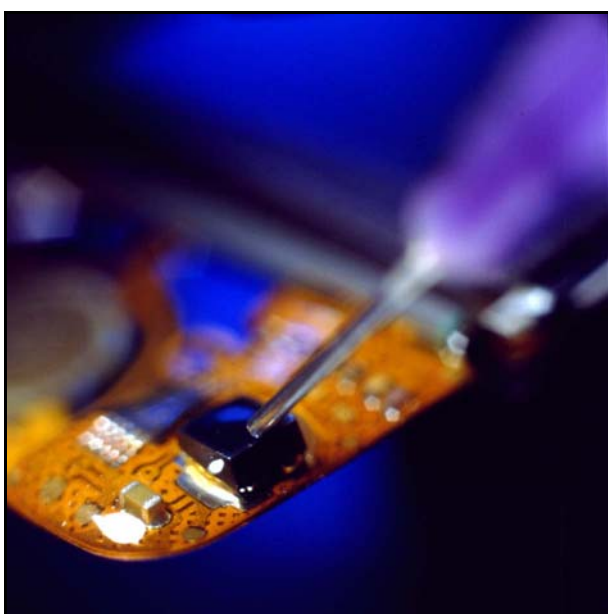


# CHIP ENCAPSULANTS

## for Superior Protection on Flexible and Rigid Platforms

Tough, flexible UV light curing encapsulants are easily incorporated into automated systems and cure in seconds without slowing down microelectronic assembly. DYMAX 9000 Series encapsulants have high ionic purity, and resistance to humidity and thermal shock to effectively protect components improve their reliability. Single component encapsulants contain no sharp, abrasive mineral or glass fillers to abrade fine wires, and their combination of low  $T_g$  and low modulus means low stress. Ultraviolet light curing encapsulants have excellent adhesion to Polyimide, PET, flexible printed circuits, FR4 and ceramic boards and provide superior protection for glob top and chip-on-board applications. 9000 series encapsulants are ideal for encapsulating IC's in flex circuits. Clear and black grades of encapsulants are available in a wide range of viscosities, from thin wicking to non-flowing gel.



Clear UV Curing Encapsulants

### KEY FEATURES

- ❖ Instant UV/visible cure
- ❖ 100% solvent-free
- ❖ High ionic purity
- ❖ Excellent adhesion to flex circuit substrates (Polyimide and PET)
- ❖ Thermal shock and moisture resistance
- ❖ Low stress under thermal cycling
- ❖ Electrically insulating
- ❖ Room temperature storage

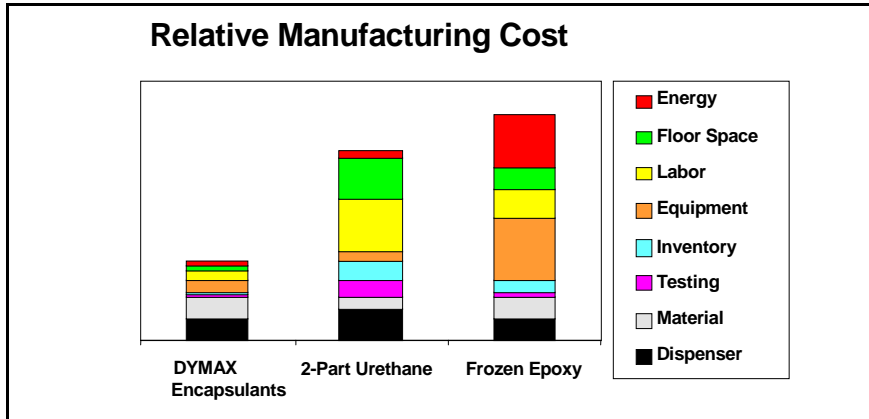
Product	Features	Application	Durometer Hardness	Viscosity (cP)	Elongation at Break	Modulus of Elasticity
9001-E-v3.0	Low viscosity, sprayable grade, 9001-E Series encapsulant	Sprayable Coating/Chip Encapsulant	D45	400	150%	2,500 psi
9001-E-v3.1	General purpose, medium viscosity encapsulant, good adhesion to flexible and rigid printed circuits	Chip Encapsulant	D45	4,500	150%	2,500 psi
9001-E-v3.5	Higher viscosity 9001-E Series encapsulant	Chip Encapsulant	D45	17,000	150%	2,500 psi
9001-E-v3.7	Thixotropic viscosity encapsulant	Dam or Thick Coatings	D45	50,000	150%	2,500 psi
9008	More flexible version of 9001-E-v3.1 for difficult substrates	Chip Encapsulant	A80 – 90	4,500	300%	2,000 psi
9-20558	UV curing, flexible, moisture barrier coating for metal, ceramic, epoxy and glass filled plastics	Strain Relief or Chip Encapsulant	D45	20,000	75%	3,500 psi

## HIGH IONIC PURITY

Typical Ionic Content		
Extractable Chloride	<10 ppm	IC
Sodium	<10 ppm	ICP
Potassium	<10 ppm	AA
Fluoride	<10 ppm	IC



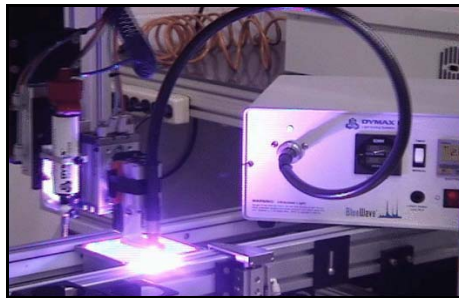
IC Kapton  
Flex Circuit Encapsulant



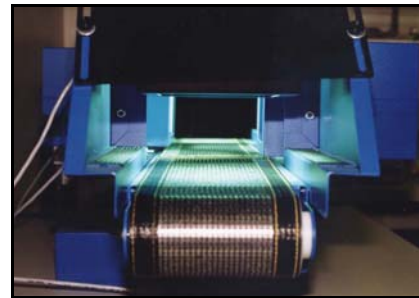
Glob Top and  
Black Encapsulants

## CURING OPTIONS for DYMAX ENCAPSULANTS

DYMAX encapsulants cure in seconds upon exposure to UV light, affording the fastest processing possible. Avoid processing bottlenecks by choosing an efficient and cost effective DYMAX encapsulant with a matched DYMAX UV light curing system.



Automated DYMAX spot curing system  
mounted on XYZ dispenser



Cure large parts or arrays of parts under high  
intensity conveyerized curing systems

*For further assistance with adhesive and equipment selection, contact your DYMAX Applications Engineer.*

In the U.S. Call: 877.396.2988  
In North and South America Call: 860.482.1010  
In Europe Call: 0049.69.7165.3568  
In Asia Call: 852.2460.7038

[www.dymax.com](http://www.dymax.com)

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